

L Number	Hits	Search Text	DB	Time stamp
9	2	6185815.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/07/07 15:02
10	47	("Re34615" "3337941" "4144449" "4346293" "4351264" "4378134" "4383359" "4584047" "4610083" "4615093" "4819326" "4938653" "5049029" "5150423" "5157734" "5191693" "5195234" "5213653" "5248362" "5249239" "5275657" "5278634" "5289625" "5309223" "5311304" "5342460" "5380099" "5400497" "5415693" "5459794" "5475919" "5488771" "5499756" "5515600" "5516026" "5547537" "5559727" "5564188" "5592562" "5650081" "5669970" "5708419" "5715594" "5735040" "5788379" "5885052" "6077022").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/07/07 15:00
11	8	flip adj chip near device and drive near system	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 15:42
12	251	flip adj chip near device and drive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 15:07
13	13	flip adj chip near device and drive and 29/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 15:33
14	36	("3317106" "3692225" "3938722" "4084315" "4489821" "4626167" "4768702" "4776080" "4878610" "4921397" "4980971" "5022580" "5044072" "5054991" "5084959" "5113565" "5115559" "5233745" "5311304" "5351876" "5368217" "5370301" "5377897" "5454160" "5460320" "5462217" "5482198" "5535526" "5579980" "5743005" "5744869" "5759268" "5768759" "5864943" "5870820" "5992013").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/07/07 15:13
15	4	("4738025" "4912843" "4922434" "4980971").PN.	USPAT	2004/07/07 15:21
16	4	("4342090" "4598456" "4663658" "4675993").PN.	USPAT	2004/07/07 15:22

17	7	("3815204" "4127936" "4146924" "4305130" "4396945" "4412293" "4472668").PN.	USPAT	2004/07/07 15:24
18	106	4146924.URPN.	USPAT	2004/07/07 15:31
19	0	flip adj chip near device and drive and parallelogram near construction	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 15:34
20	0	flip adj chip near device and drive and parallelogram	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 15:34
21	7965	Hartmann .inv.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 15:34
22	1056	Hartmann .inv. and apparatus	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 15:34
23	0	Hartmann .inv. and apparatus near flip adj chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 15:35
24	0	Hartmann .inv. and apparatus near flip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 15:35
25	3	Hartmann .inv. and apparatus and flip near chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 15:35
26	1	1256974.URPN.	USPAT	2004/07/07 15:36
27	9	mounting near device and drive near system and (29/739; 29/740 ; 29/741 ; 198/468.4 ; 198/468.2 ; 414/752 ; 414/753 ; 414/751 ; 414/225 ; 414/226 ; 414/744.6).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 16:00
28	2	4601627.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 16:00

29	2	5049029.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 16:01
30	2	5084959.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 16:13
31	38	5084959.URPN.	USPAT	2004/07/07 16:02
32	7	("4598456" "5084959" "5115559" "5172468" "5206985" "5420691" "5456001").PN.	USPAT	2004/07/07 16:06
33	4	("4738025" "4912843" "4922434" "4980971").PN.	USPAT	2004/07/07 16:08
34	7	("4342090" "4628464" "4641257" "4720635" "4723221" "4737845" "4780617").PN.	USPAT	2004/07/07 16:09
35	3	("3986007" "4017721" "4146924").PN.	USPAT	2004/07/07 16:10
36	8	("3216311" "3454169" "3589134" "3669549" "3804270" "3850313" "3888362" "3890552").PN.	USPAT	2004/07/07 16:12
37	31	die adj bond\$3 near apparatus and flip near chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 16:23
38	8	Hartmann near Dominik .inv.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 16:15
39	18	("3467430" "4318222" "4404741" "4867569" "4887351" "4951383" "5018936" "5033783" "5093983" "RE33974" "5172468" "5201696" "5222293" "5251266" "5341563" "5471742" "5590456" "6203082").PN.	USPAT	2004/07/07 16:19
40	17	("Re33974" "3467430" "4318222" "4404741" "4867569" "4887351" "4951383" "5018936" "5033783" "5093983" "5172468" "5201696" "5222293" "5251266" "5341563" "5471742" "5590456").PN.	USPAT	2004/07/07 16:22
41	7	die adj bond\$3 near apparatus and flip near chip and (294/64.1; 294/66.2 ; 294/907 ; 29/720 ; 29/721 ; 29/740 ; 29/743 ; 269/21 ; 279/3 ; 414/737 ; 414/752 ; 901/40 ; 901/47).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/07 16:24

	Title	Current OR
1	Apparatus for placing a semiconductor chip as a flipchip on a substrate	29/740
2	Electric-component transferring apparatus, method of taking images of electric components, and electric-component mounting system	29/833
3	Electric-component transferring apparatus	29/740
4	Electronic component mounting device	29/740
5	Circuit-component mounting system	29/740
6	Electronic parts-mounting apparatus	29/740
7	Surface mounted component transport mechanism	29/740
8	Multi-lead component manipulator	318/568.11
9	Automatic part insertion machine	29/741

	Current XRef
1	29/739; 29/840
2	29/593; 29/740; 29/742; 29/743
3	29/741; 29/742; 29/743; 29/832; 29/833; 29/834; 29/DIG.44
4	29/721; 29/741; 29/743
5	198/586; 29/741; 29/832
6	29/741; 29/743; 294/64.1
7	29/759
8	29/741; 29/833; 294/86.4; 294/907; 318/568.16; 318/640; 414/730
9	198/345.1; 29/759; 29/836; 29/838